

60V N-Channel Enhancement Mode MOSFET

Description

The NP6003VR uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

General Features

- ◆ $V_{DS} = 60V \quad I_D = 3A$
 $R_{DS(ON)} = 78m\Omega \quad @ V_{GS} = 10V \quad (\text{Typ: } 76m\Omega)$
 $R_{DS(ON)} = 88m\Omega \quad @ V_{GS} = 4.5V \quad (\text{Typ: } 88m\Omega)$
- ◆ High density cell design for ultra low $R_{DS(on)}$.
- ◆ Fully characterized avalanche voltage and current.
- ◆ Low gate to drain charge to reduce switching losses.

Application

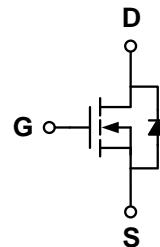
- ◆ Power switching application.
- ◆ Hard switched and high frequency circuits.
- ◆ Uninterruptible power supply.

Package

- ◆ SOT-23

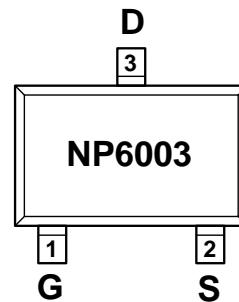


Schematic diagram



Marking and pin assignment

SOT-23
(TOP VIEW)



Ordering Information

Part Number	Storage Temperature	Package	Devices Per Reel
NP6003VR-G	-55°C to +150°C	SOT-23	3000

Absolute Maximum Ratings (TA=25°C unless otherwise noted)

parameter	symbol	limit	unit
Drain-source voltage	V_{DS}	60	V
Gate-source voltage	V_{GS}	± 20	V
Continuous Drain Current ($T_J = 150^\circ C$)	$T_C = 25^\circ C$	3	A
	$T_C = 70^\circ C$	2	
	$T_A = 25^\circ C$	1.6 ^{b,c}	
	$T_A = 70^\circ C$	1.3 ^{b,c}	
Continuous Source-Drain Diode Current	$T_C = 25^\circ C$	2.1	A
	$T_A = 25^\circ C$	1 ^{b,c}	
Pulsed Drain Current ($t = 300 \mu s$)	I_{DM}	12	
Maximum power dissipation	P_D	2.5	W

	T _C =70°C		1.6	
	T _A =25°C		1.25 ^{b,c}	
	T _A =70°C		0.8 ^{b,c}	
Operating Junction and Storage Temperature Range		T _J , T _{STG}	-55—150	°C

Thermal Characteristics

Parameter	Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient ^{b, d}	R _{θJA}	100	130	°C/W
Maximum Junction-to-Foot (Drain)	R _{θJF}	60	75	

Notes:

a:T_C = 25 °C. b:Surface mounted on 1" x 1" FR4 board.

c:t = 5 s. d: Maximum under steady state conditions is 175 °C/W.

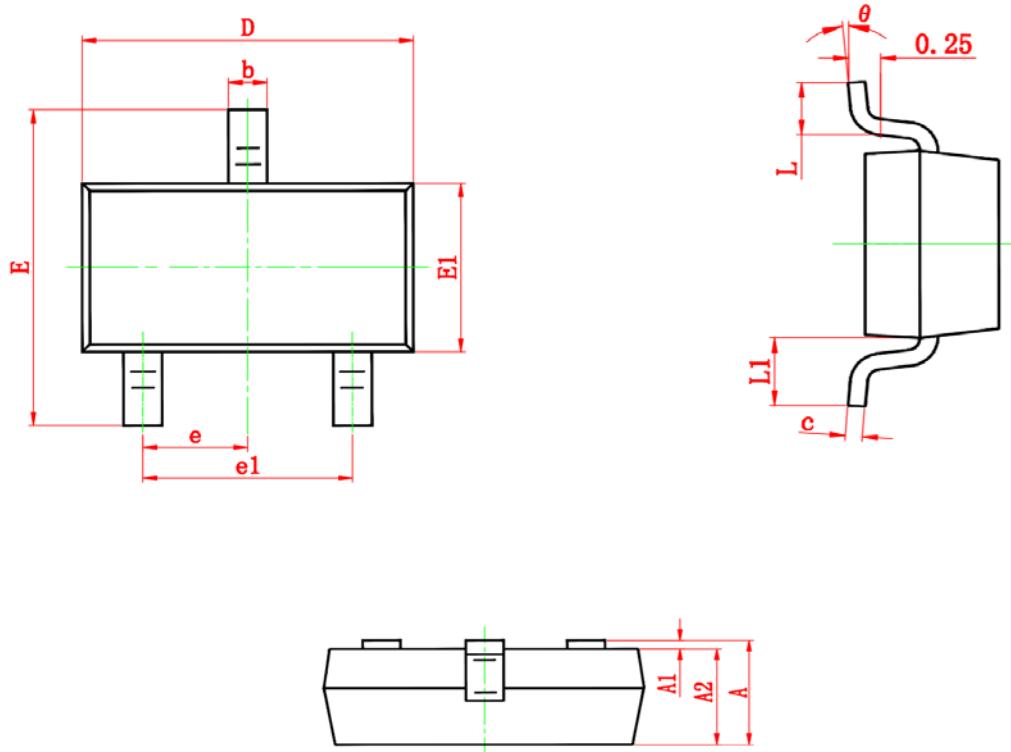
Electrical Characteristics (TA=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Static Characteristics						
Drain-source breakdown voltage	BV _{DSS}	V _{GS} =0V, I _D =250μA	60	-	-	V
BVDSS Temperature Coefficient	△BV _{DSS} /△T _J	Reference to 25°C, ID=1mA		33		mV/°C
Zero gate voltage drain current	I _{DSS}	V _{DS} =60V, V _{GS} =0V	-	-	1	μA
		T _J =85°C	-	-	30	
Gate Leakage Current	I _{GSS}	V _{DS} =0V, V _{GS} =±20V	-	-	±100	nA
Gate threshold voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	1.2	1.9	2.5	V
Drain-source on-state resistance ¹	R _{DS(ON)}	V _{GS} =10V, I _D =3A	-	78	90	mΩ
		V _{GS} =4.5V, I _D =2A		88	100	
On Status Drain Current	I _{D(ON)}	V _{DS} =10V, V _{GS} =10V	3	-	-	A
Diode Characteristics						
Diode Forward Voltage	V _{SD}	I _{SD} =1A, V _{GS} =0V	-	0.75	1.1	V
Diode Continuous Forward Current	I _S		-	-	3	A
Reverse Recovery Time	t _{rr}	I _F =1.5A, dI/dt=100A/us	-	15	-	ns
Reverse Recovery Charge	Q _{rr}		-	12	-	nC
Dynamic Characteristics²						
Gate Resistance	R _G	V _{GS} =0V, V _{DS} =0V, f=1MHz	-	2.0	-	Ω
Input capacitance	C _{ISS}	V _{GS} =0V, V _{DS} =25V f=1.0MHz	-	175	-	pF
Output capacitance	C _{OSS}		-	21	-	
Reverse transfer capacitance	C _{RSS}		-	13	-	
Turn-on delay time	t _{D(ON)}	V _{GS} =10V, V _{DD} =30V, R _L =4.7Ω, I _D =1.5A, R _G =3.3Ω	-	15	-	ns
Turn-on Rise time	t _r		-	16	-	
Turn-off delay time	t _{D(OFF)}		-	10	-	
Turn-off Fall time	t _f		-	10	-	

Total gate charge	Q_g	$V_{GS}=10V, I_D=2A$ $V_{DS}=30V$	-	4.1		nC
Gate-source charge	Q_{gs}			0.8		
Gate-drain charge	Q_{gd}		-	1	-	

Package Information

- SOT-23



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	2.250	2.550	0.089	0.100
E1	1.200	1.400	0.047	0.055
e	0.950 TYP.		0.037 TYP.	
e1	1.800	2.000	0.071	0.079
L	0.300	0.500	0.012	0.020
L1	0.550 REF.		0.022 REF.	
θ	0°	8°	0°	8°